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- 4.5-V to 5.5-V V_{CC} Operation
- Wide Operating Temperature Range of -55°C to 125°C
- Balanced Propagation Delays and Transition Times
- Standard Outputs Drive Up To 10 LS-TTL Loads
- Significant Power Reduction Compared to LS-TTL Logic ICs
- Inputs Are TTL-Voltage Compatible

CD54HCT258...F PACKAGE CD74HCT258...E PACKAGE (TOP VIEW) 16 VCC Ā/B G 1A 15 ∏ 1B 14**∏** 4A 1Y 13 AB 2A 12**∏** 4Y 2B П6 11 T 3A 2Y 10 3B GND 9 🛮 3Y

description/ordering information

These devices are designed to multiplex signals from 4-bit data sources to 4-output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable (\overline{G}) input is at a high logic level.

To ensure the high-impedance state during power up or power down, \overline{G} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING		
55°C to 125°C	-55°C to 125°C PDIP – E Tube	Tube	CD74HCT258E	CD74HCT258E		
-55 C to 125 C	CDIP – F		CD54HCT258F3A			

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	INPU	JTS		OUTPUT
G	Ā/B	Α	В	Y
Н	Х	Χ	Х	Z
L	L	L	Χ	Н
L	L	Н	Χ	L
L	Н	Χ	L	Н
L	Н	Χ	Н	L

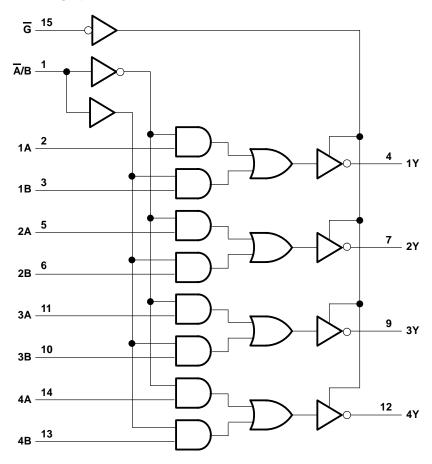


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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output drain current per output, $I_O(V_O = 0 \text{ to } V_{CC})$	±35 mA
Continuous output source or sink current per output, I_O ($V_O = 0$ to V_{CC})	
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 2): E package	69°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
٧ _I	Input voltage		VCC	V
٧o	Output voltage		VCC	V
Δt/Δν	Input transition rise or fall rate		500	ns
TA	Operating free-air temperature	-55	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		vcc	T _A = 25°C		T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
\/o	\\ \\ or \\.	I _{OH} = -20 μA	4.5 V	4.4		4.4		4.4		V
VOH	VI = VIH or VIL	$I_{OH} = -6 \text{ mA}$	4.5 V	3.98		3.7		3.84		V
Voi	//. = \/ or \/	I _{OL} = 20 μA	4.5 V		0.1		0.1		0.1	V
VOL	$V_I = V_{IH}$ or V_{IL}	$I_{OL} = 6 \text{ mA}$	4.5 V		0.26		0.4		0.33	V
lį	VI = ACC or 0		5.5 V		±0.1		±1		±1	μΑ
loz	$V_O = V_{CC}$ or 0		5.5 V		±0.5		±10		±5	μΑ
ICC	$V_I = V_{CC}$ or 0, $I_O = 0$		5.5 V		8		160		80	μΑ
∆l _{CC} †	One input at V _{CC} – 2.1 V, Other inputs at 0 or V _{CC}		4.5 V to 5.5 V	100	360		490		450	μΑ
C _i				10		10		10	pF	
Co					20		20		20	pF

 $[\]dot{T}$ Additional quiescent supply current per input pin, TTL inputs high, 1 unit load. For dual-supply systems, theoretical worst-case ($V_I = 2.4 \text{ V}$, $V_{CC} = 5.5 \text{ V}$) specification is 1.8 mA.

HCT INPUT LOADING TABLE

INPUT	UNIT LOAD
G	1.5
A or B	0.5
Ā/B	1.5

Unit Load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 360 μA max at 25°C).



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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM TO (INPUT)		LOAD CAPACITANCE	Vcc	T _A = 25°C			T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		UNIT		
	(INFO1)	(001F01)	CAFACITANCE		MIN	TYP	MAX	MIN	MAX	MIN	MAX			
	A or B	Any V	C _L = 50 pF	4.5 V			27		41		34			
	AUID	Any Y	C _L = 15 pF	5 V		11								
^t pd	Ā/B	Any Y	C _L = 50 pF	4.5 V			34		51		43	ns		
			C _L = 15 pF	5 V		14								
t _{en} G	_	Any Y	C _L = 50 pF	4.5 V			28		42		35	20		
	G		Ally I	Ally I	Ally I	Ally I	C _L = 15 pF	5 V		11				
^t dis	G	G Any Y	C _L = 50 pF	4.5 V			30		45		38			
			C _L = 15 pF	5 V		12			·			ns		
t _t		Any Y	C _L = 50 pF				12		18		15	ns		

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER	TYP	UNIT
C _{pd} Power dissipation capacitance per multiplexer [†]	49	pF

† C_{pd} is used to determine the dynamic power consumption per multiplexer.

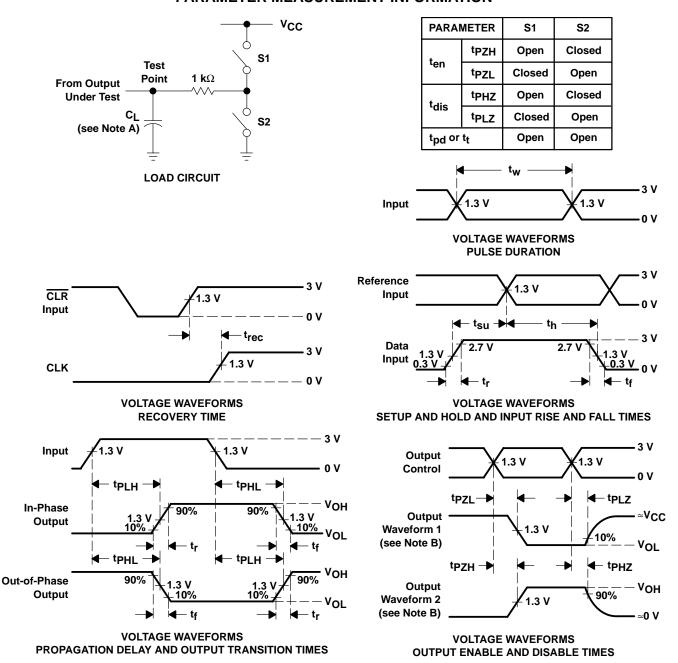
 $P_D = V_{CC}^2 fi (C_{pd} + C_L)$ where: $P_D =$ dynamic power dissipation

fi = input frequency

C_L = output load capacitance V_{CC} = supply voltage

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PARAMETER MEASUREMENT INFORMATION

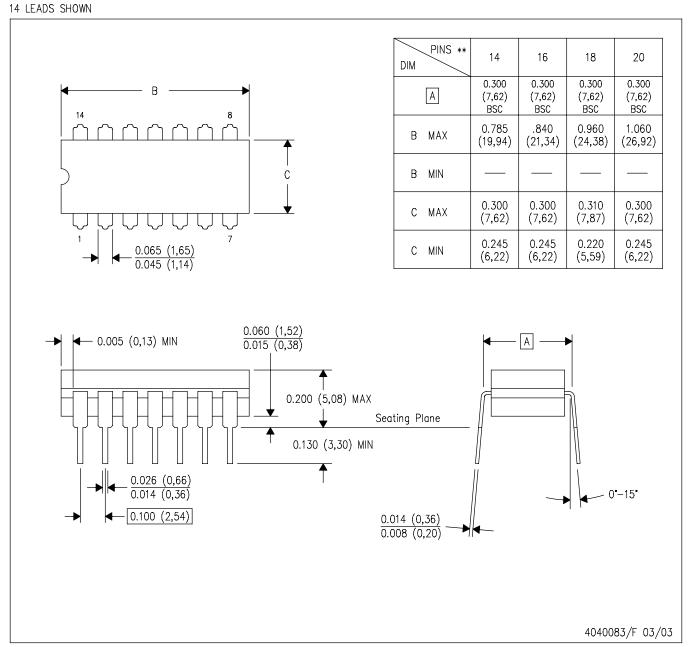


NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. t_{PZL} and t_{PZH} are the same as t_{en} .
- H. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





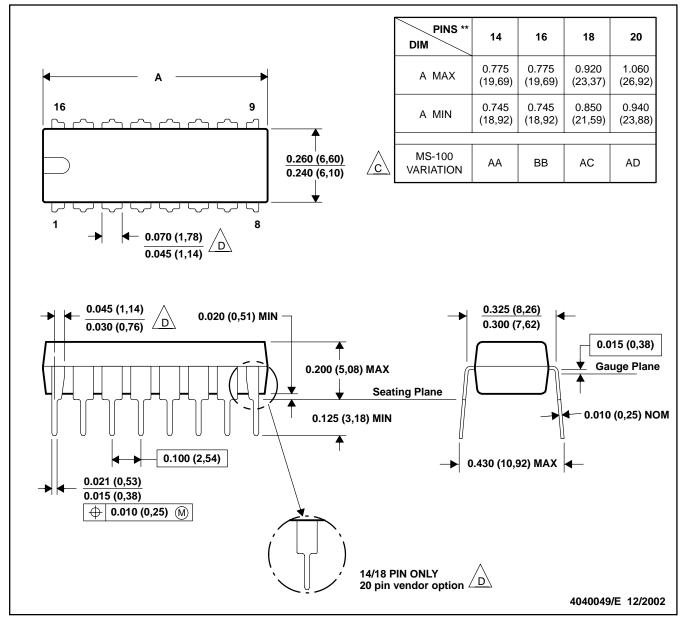
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

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